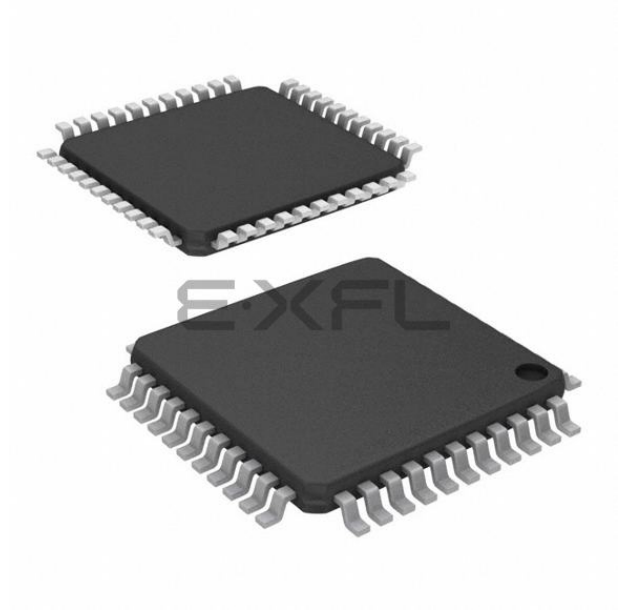

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Program Memory Type	FLASH
EEPROM Size	-
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 8x12b
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
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Package / Case	44-LQFP
Supplier Device Package	44-LQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/mc9s08jm32cld

Contents

Chapter 5
Resets, Interrupts, and System Configuration

5.1 Introduction

This chapter discusses basic reset and interrupt mechanisms and the various sources of reset and interrupts in the MC9S08JM60 series. Some interrupt sources from peripheral modules are discussed in greater detail within other chapters of this data manual. This chapter gathers basic information about all reset and interrupt sources in one place for easy reference. A few reset and interrupt sources, including the computer operating properly (COP) watchdog, are not part of on-chip peripheral systems with their own sections but are part of the system control logic.

5.2 Features

Reset and interrupt features include:

- Multiple sources of reset for flexible system configuration and reliable operation
- Reset status register (SRS) to indicate source of most recent reset
- Separate interrupt vectors for each module (reduces polling overhead) (see Table 5-1)

5.3 MCU Reset

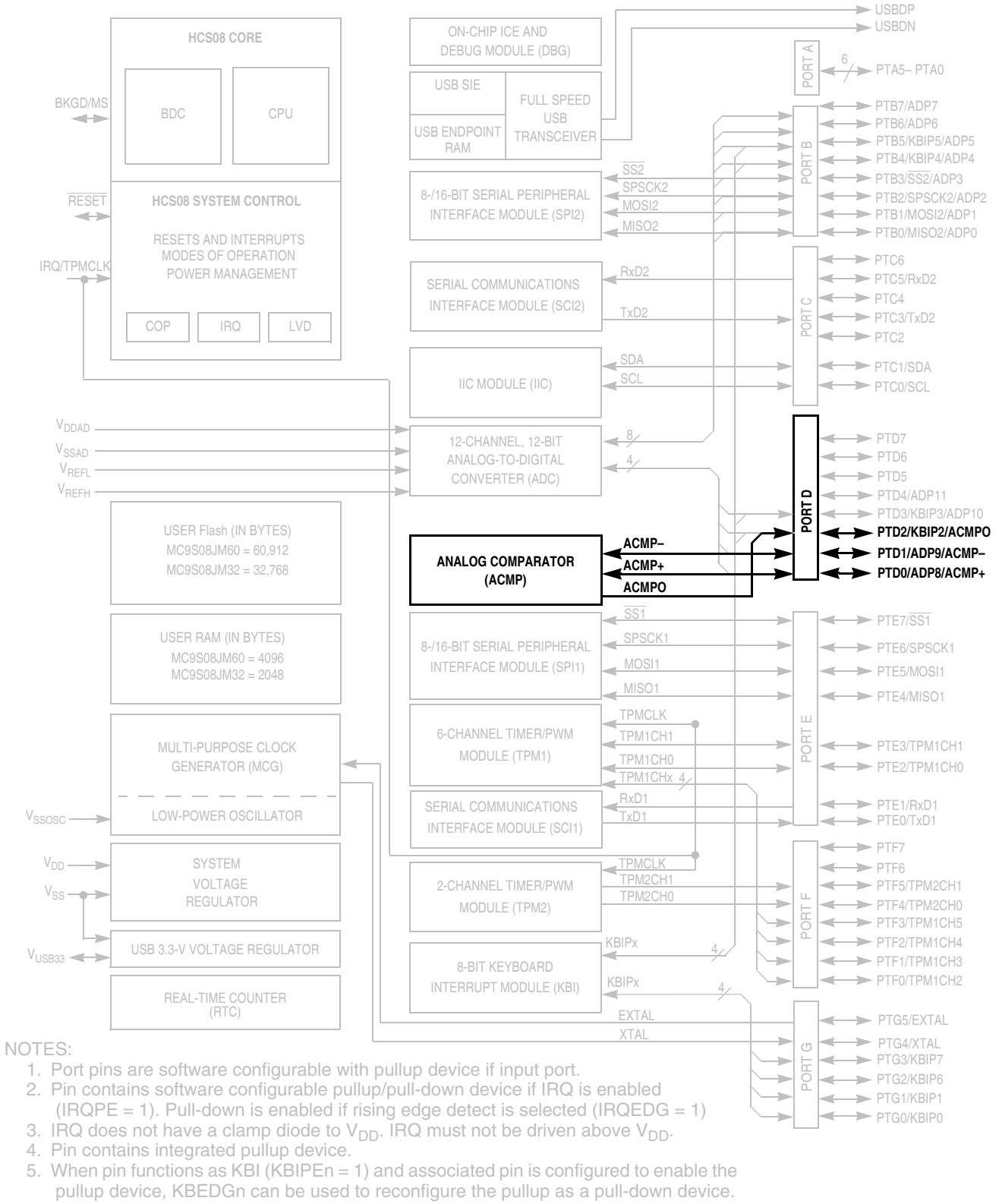
Resetting the MCU provides a way to start processing from a known set of initial conditions. During reset, most control and status registers are forced to initial values and the program counter is loaded from the reset vector (0xFFFE:0xFFFF). On-chip peripheral modules are disabled and I/O pins are initially configured as general-purpose high-impedance inputs with pullup devices disabled. The I bit in the condition code register (CCR) is set to block maskable interrupts so the user program has a chance to initialize the stack pointer (SP) and system control settings. SP is forced to 0x00FF at reset.

The MC9S08JM60 series has seven sources for reset:

- Power-on reset (POR)
- Low-voltage detect (LVD)
- Computer operating properly (COP) timer
- Illegal opcode detect (ILOP)
- Background debug forced reset
- External reset pin ($\overline{\text{RESET}}$)
- Clock generator loss of lock and loss of clock reset (LOC)

Table 7-2. . Instruction Set Summary (Sheet 7 of 9)

Source Form	Operation	Address Mode	Object Code	Cycles	Cyc-by-Cyc Details	Affect on CCR	
						VH	I N Z C
RSP	Reset Stack Pointer (Low Byte) SPL ← $FF (High Byte Not Affected)	INH	9C	1	p	– –	– – – –
RTI	Return from Interrupt SP ← (SP) + $0001; Pull (CCR) SP ← (SP) + $0001; Pull (A) SP ← (SP) + $0001; Pull (X) SP ← (SP) + $0001; Pull (PCH) SP ← (SP) + $0001; Pull (PCL)	INH	80	9	uuuuufppp	↕ ↕	↕ ↕ ↕ ↕
RTS	Return from Subroutine SP ← SP + $0001; Pull (PCH) SP ← SP + $0001; Pull (PCL)	INH	81	5	ufppp	– –	– – – –
SBC #*opr8i* SBC *opr8a* SBC *opr16a* SBC *oprx16*,X SBC *oprx8*,X SBC ,X SBC *oprx16*,SP SBC *oprx8*,SP	Subtract with Carry A ← (A) – (M) – (C)	IMM DIR EXT IX2 IX1 IX SP2 SP1	A2 ii B2 dd C2 hh ll D2 ee ff E2 ff F2 9E D2 ee ff 9E E2 ff	2 3 4 4 3 3 5 4	pp rpp prpp prpp rpp rfp pprpp prpp	↕ –	– ↕ ↕ ↕
SEC	Set Carry Bit (C ← 1)	INH	99	1	p	– –	– – – 1
SEI	Set Interrupt Mask Bit (I ← 1)	INH	9B	1	p	– –	1 – – –
STA *opr8a* STA *opr16a* STA *oprx16*,X STA *oprx8*,X STA ,X STA *oprx16*,SP STA *oprx8*,SP	Store Accumulator in Memory M ← (A)	DIR EXT IX2 IX1 IX SP2 SP1	B7 dd C7 hh ll D7 ee ff E7 ff F7 9E D7 ee ff 9E E7 ff	3 4 4 3 2 5 4	wpp pwpp pwpp wpp wp ppwpp pwpp	0 –	– ↕ ↕ –
STHX *opr8a* STHX *opr16a* STHX *oprx8*,SP	Store H:X (Index Reg.) (M:M + $0001) ← (H:X)	DIR EXT SP1	35 dd 96 hh ll 9E FF ff	4 5 5	wwpp pwwpp pwwpp	0 –	– ↕ ↕ –
STOP	Enable Interrupts: Stop Processing Refer to MCU Documentation I bit ← 0; Stop Processing	INH	8E	2	fp...	– –	0 – – –
STX *opr8a* STX *opr16a* STX *oprx16*,X STX *oprx8*,X STX ,X STX *oprx16*,SP STX *oprx8*,SP	Store X (Low 8 Bits of Index Register) in Memory M ← (X)	DIR EXT IX2 IX1 IX SP2 SP1	BF dd CF hh ll DF ee ff EF ff FF 9E DF ee ff 9E EF ff	3 4 4 3 2 5 4	wpp pwpp pwpp wpp wp ppwpp pwpp	0 –	– ↕ ↕ –



NOTES:
1. Port pins are software configurable with pullup device if input port.
2. Pin contains software configurable pullup/pull-down device if IRQ is enabled (IRQPE = 1). Pull-down is enabled if rising edge detect is selected (IRQEDG = 1)
3. IRQ does not have a clamp diode to V_{DD}. IRQ must not be driven above V_{DD}.
4. Pin contains integrated pullup device.
5. When pin functions as KBI (KBIPEn = 1) and associated pin is configured to enable the pullup device, KBEDGn can be used to reconfigure the pullup as a pull-down device.

Figure 8-1. MC9S08JM60 Series Block Diagram Highlighting ACMP Block and Pins

Table 10-6. ADCCFG Register Field Descriptions (continued)

Field	Description
3:2 MODE	Conversion Mode Selection. MODE bits are used to select between 12-, 10-, or 8-bit operation. See Table 10-8.
1:0 ADICLK	Input Clock Select. ADICLK bits select the input clock source to generate the internal clock ADCK. See Table 10-9.

Table 10-7. Clock Divide Select

ADIV	Divide Ratio	Clock Rate
00	1	Input clock
01	2	Input clock ÷ 2
10	4	Input clock ÷ 4
11	8	Input clock ÷ 8

Table 10-8. Conversion Modes

MODE	Mode Description
00	8-bit conversion (N=8)
01	12-bit conversion (N=12)
10	10-bit conversion (N=10)
11	Reserved

Table 10-9. Input Clock Select

ADICLK	Selected Clock Source
00	Bus clock
01	Bus clock divided by 2
10	Alternate clock (ALTCLK)
11	Asynchronous clock (ADACK)

10.3.8 Pin Control 1 Register (APCTL1)

The pin control registers disable the I/O port control of MCU pins used as analog inputs. APCTL1 is used to control the pins associated with channels 0–7 of the ADC module.

	7	6	5	4	3	2	1	0
R W	ADPC7	ADPC6	ADPC5	ADPC4	ADPC3	ADPC2	ADPC1	ADPC0
Reset:	0	0	0	0	0	0	0	0

Figure 10-10. Pin Control 1 Register (APCTL1)

10.4.1 Clock Select and Divide Control

One of four clock sources can be selected as the clock source for the ADC module. This clock source is then divided by a configurable value to generate the input clock to the converter (ADCK). The clock is selected from one of the following sources by means of the ADICLK bits.

- The bus clock, which is equal to the frequency at which software is executed. This is the default selection following reset.
- The bus clock divided by two. For higher bus clock rates, this allows a maximum divide by 16 of the bus clock.
- ALTCLK, as defined for this MCU (See module section introduction).
- The asynchronous clock (ADACK). This clock is generated from a clock source within the ADC module. When selected as the clock source, this clock remains active while the MCU is in wait or stop3 mode and allows conversions in these modes for lower noise operation.

Whichever clock is selected, its frequency must fall within the specified frequency range for ADCK. If the available clocks are too slow, the ADC do not perform according to specifications. If the available clocks are too fast, the clock must be divided to the appropriate frequency. This divider is specified by the ADIV bits and can be divide-by 1, 2, 4, or 8.

10.4.2 Input Select and Pin Control

The pin control registers (APCTL3, APCTL2, and APCTL1) disable the I/O port control of the pins used as analog inputs.When a pin control register bit is set, the following conditions are forced for the associated MCU pin:

- The output buffer is forced to its high impedance state.
- The input buffer is disabled. A read of the I/O port returns a zero for any pin with its input buffer disabled.
- The pullup is disabled.

10.4.3 Hardware Trigger

The ADC module has a selectable asynchronous hardware conversion trigger, ADHWT, that is enabled when the ADTRG bit is set. This source is not available on all MCUs. Consult the module introduction for information on the ADHWT source specific to this MCU.

When ADHWT source is available and hardware trigger is enabled (ADTRG=1), a conversion is initiated on the rising edge of ADHWT. If a conversion is in progress when a rising edge occurs, the rising edge is ignored. In continuous convert configuration, only the initial rising edge to launch continuous conversions is observed. The hardware trigger function operates in conjunction with any of the conversion modes and configurations.

10.4.4 Conversion Control

Conversions can be performed in 12-bit mode, 10-bit mode, or 8-bit mode as determined by the MODE bits. Conversions can be initiated by a software or hardware trigger. In addition, the ADC module can be

Chapter 11
Inter-Integrated Circuit (S08IICV2)

11.1 Introduction

The MC9S08JM60 series of microcontrollers has an inter-integrated circuit (IIC) module for communication with other integrated circuits. The two pins associated with this module, SCL and SDA, are shared with PTC0 and PTC1, respectively.

NOTE

MC9S08JM60 series devices operate at a higher voltage range (2.7 V to 5.5 V) and do not include stop1 mode. Therefore, please disregard references to stop1.

12.3.2 MCG Control Register 2 (MCGC2)

	7	6	5	4	3	2	1	0
R W	BDIV		RANGE	HGO	LP	EREFS	ERCLKEN	EREFSTEN
Reset:	0	1	0	0	0	0	0	0

Figure 12-4. MCG Control Register 2 (MCGC2)

Table 12-2. MCG Control Register 2 Field Descriptions

Field	Description
7:6 BDIV	**Bus Frequency Divider** — Selects the amount to divide down the clock source selected by the CLKS bits in the MCGC1 register. This controls the bus frequency. 00 Encoding 0 — Divides selected clock by 1 01 Encoding 1 — Divides selected clock by 2 (reset default) 10 Encoding 2 — Divides selected clock by 4 11 Encoding 3 — Divides selected clock by 8
5 RANGE	**Frequency Range Select** — Selects the frequency range for the external oscillator or external clock source. 1 High frequency range selected for the external oscillator of 1 MHz to 16 MHz (1 MHz to 40 MHz for external clock source) 0 Low frequency range selected for the external oscillator of 32 kHz to 100 kHz (32 kHz to 1 MHz for external clock source)
4 HGO	**High Gain Oscillator Select** — Controls the external oscillator mode of operation. 1 Configure external oscillator for high gain operation 0 Configure external oscillator for low power operation
3 LP	**Low Power Select** — Controls whether the FLL (or PLL) is disabled in bypassed modes. 1 FLL (or PLL) is disabled in bypass modes (lower power). 0 FLL (or PLL) is not disabled in bypass modes.
2 EREFS	**External Reference Select** — Selects the source for the external reference clock. 1 Oscillator requested 0 External Clock Source requested
1 ERCLKEN	**External Reference Enable** — Enables the external reference clock for use as MCGERCLK. 1 MCGERCLK active 0 MCGERCLK inactive
0 EREFSTEN	**External Reference Stop Enable** — Controls whether or not the external reference clock remains enabled when the MCG enters stop mode. 1 External reference clock stays enabled in stop if ERCLKEN is set or if MCG is in FEE, FBE, PEE, PBE, or BLPE mode before entering stop 0 External reference clock is disabled in stop

external crystal and a maximum reference divider factor of 128, the resulting frequency of the reference clock for the FLL is 62.5 kHz (greater than the 39.0625 kHz maximum allowed).

Care must be taken in the software to minimize the amount of time spent in this state where the FLL is operating in this condition.

The following code sequence describes how to move from FEI mode to PEE mode until the 8 MHz crystal reference frequency is set to achieve a bus frequency of 8 MHz. Because the MCG is in FEI mode out of reset, this example also shows how to initialize the MCG for PEE mode out of reset. First, the code sequence will be described. Then a flowchart will be included which illustrates the sequence.

1. First, FEI must transition to FBE mode:
   a) MCGC2 = 0x36 (%00110110)
      – BDIV (bits 7 and 6) set to %00, or divide-by-1
      – RANGE (bit 5) set to 1 because the frequency of 8 MHz is within the high frequency range
      – HGO (bit 4) set to 1 to configure external oscillator for high gain operation
      – EREFS (bit 2) set to 1, because a crystal is being used
      – ERCLKEN (bit 1) set to 1 to ensure the external reference clock is active
   b) Loop until OSCINIT (bit 1) in MCGSC is 1, indicating the crystal selected by the EREFS bit has been initialized.
   c) Block Interrupts (If applicable by setting the interrupt bit in the CCR).
   d) MCGC1 = 0xB8 (%10111000)
      – CLKS (bits 7 and 6) set to %10 in order to select external reference clock as system clock source
      – RDIV (bits 5-3) set to %111, or divide-by-128.

NOTE

8 MHz / 128 = 62.5 kHz which is greater than the 31.25 kHz to 39.0625 kHz range required by the FLL. Therefore after the transition to FBE is complete, software must progress through to BLPE mode immediately by setting the LP bit in MCGC2.

      – IREFS (bit 2) cleared to 0, selecting the external reference clock
   e) Loop until IREFST (bit 4) in MCGSC is 0, indicating the external reference is the current source for the reference clock
   f) Loop until CLKST (bits 3 and 2) in MCGSC are %10, indicating that the external reference clock is selected to feed MCGOUT
2. Then, FBE mode transitions into BLPE mode:
   a) MCGC2 = 0x3E (%00111110)
      – LP (bit 3) in MCGC2 to 1 (BLPE mode entered)

NOTE

There must be no extra steps (including interrupts) between steps 1d and 2a.

   b) Enable Interrupts (if applicable by clearing the interrupt bit in the CCR).

c) MCGC1 = 0x98 (%10011000)
   - RDIV (bits 5-3) set to %011, or divide-by-8 because 8 MHz / 8= 1 MHz which is in the 1 MHz to 2 MHz range required by the PLL. In BLPE mode, the configuration of the RDIV does not matter because both the FLL and PLL are disabled. Changing them only sets up the the dividers for PLL usage in PBE mode

d) MCGC3 = 0x44 (%01000100)
   - PLLS (bit 6) set to 1, selects the PLL. In BLPE mode, changing this bit only prepares the MCG for PLL usage in PBE mode
   - VDIV (bits 3-0) set to %0100, or multiply-by-16 because 1 MHz reference * 16 = 16 MHz. In BLPE mode, the configuration of the VDIV bits does not matter because the PLL is disabled. Changing them only sets up the multiply value for PLL usage in PBE mode

e) Loop until PLLST (bit 5) in MCGSC is set, indicating that the current source for the PLLS clock is the PLL

3. Then, BLPE mode transitions into PBE mode:
   a) Clear LP (bit 3) in MCGC2 to 0 here to switch to PBE mode
   b) Then loop until LOCK (bit 6) in MCGSC is set, indicating that the PLL has acquired lock
4. Last, PBE mode transitions into PEE mode:
   a) MCGC1 = 0x18 (%00011000)
      - CLKS (bits7 and 6) in MCGSC1 set to %00 in order to select the output of the PLL as the system clock source
      - Loop until CLKST (bits 3 and 2) in MCGSC are %11, indicating that the PLL output is selected to feed MCGOUT in the current clock mode
   b) Now, With an RDIV of divide-by-8, a BDIV of divide-by-1, and a VDIV of multiply-by-16, MCGOUT = [(8 MHz / 8) * 16] / 1 = 16 MHz, and the bus frequency is MCGOUT / 2, or 8 MHz

12.5.3 Calibrating the Internal Reference Clock (IRC)

The IRC is calibrated by writing to the MCGTRM register first, then using the FTRIM bit to “fine tune” the frequency. We will refer to this total 9-bit value as the trim value, ranging from 0x000 to 0x1FF, where the FTRIM bit is the LSB.

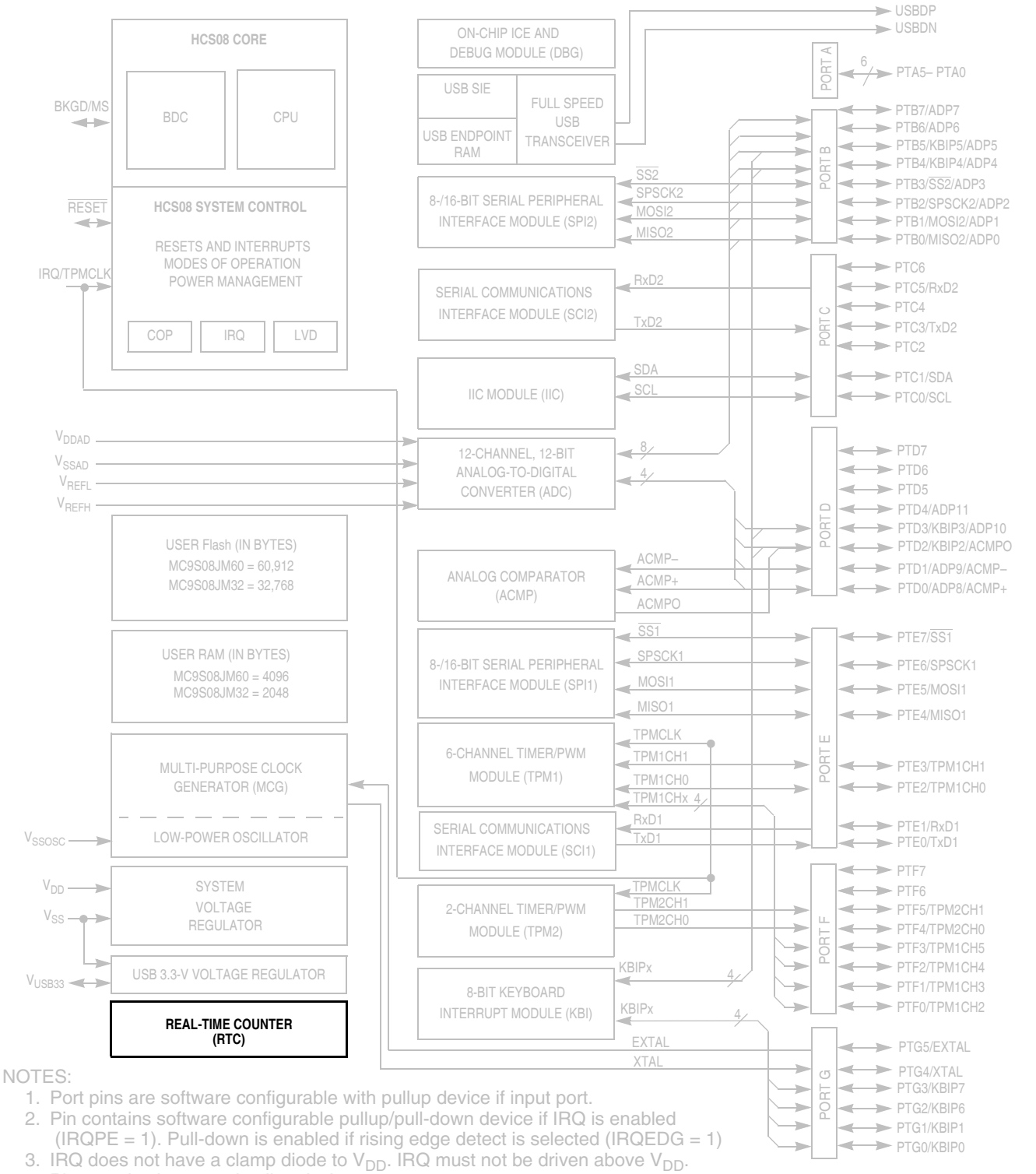
The trim value after a POR is always 0x100 (MCGTRM = 0x80 and FTRIM = 0). Writing a larger value will decrease the frequency and smaller values will increase the frequency. The trim value is linear with the period, except that slight variations in wafer fab processing produce slight non-linearities between trim value and period. These non-linearities are why an iterative trimming approach to search for the best trim value is recommended. In example #4 later in this section, this approach will be demonstrated.

After a trim value has been found for a device, this value can be stored in FLASH memory to save the value. If power is removed from the device, the IRC can easily be re-trimmed by copying the saved value from FLASH to the MCG registers. Freescale identifies recommended FLASH locations for storing the trim value for each MCU. Consult the memory map in the data sheet for these locations. On devices that are factory trimmed, the factory trim value will be stored in these locations.

12.5.3.1 Example #5: Internal Reference Clock Trim

For applications that require a tight frequency tolerance, a trimming procedure is provided that will allow a very accurate internal clock source. This section outlines one example of trimming the internal oscillator. Many other possible trimming procedures are valid and can be used.

In the example below, the MCG trim will be calibrated for the 9-bit MCGTRM and FTRIM collective value. This value will be referred to as TRMVAL.



NOTES:
1. Port pins are software configurable with pullup device if input port.
2. Pin contains software configurable pullup/pull-down device if IRQ is enabled (IRQPE = 1). Pull-down is enabled if rising edge detect is selected (IRQEDG = 1)
3. IRQ does not have a clamp diode to V_{DD}. IRQ must not be driven above V_{DD}.
4. Pin contains integrated pullup device.
5. When pin functions as KBI (KBIPEn = 1) and associated pin is configured to enable the pullup device, KBEDGn can be used to reconfigure the pullup as a pull-down device.

Figure 13-1. MC9S08JM60 Series Block Diagram Highlighting RTC Block

Table 14-3. SCIxC1 Field Descriptions (continued)

Field	Description
3 WAKE	**Receiver Wakeup Method Select** — Refer to Section 14.3.3.2, "Receiver Wakeup Operation" for more information. 0 Idle-line wakeup. 1 Address-mark wakeup.
2 ILT	**Idle Line Type Select** — Setting this bit to 1 ensures that the stop bit and logic 1 bits at the end of a character do not count toward the 10 or 11 bit times of logic high level needed by the idle line detection logic. Refer to Section 14.3.3.2.1, "Idle-Line Wakeup" for more information. 0 Idle character bit count starts after start bit. 1 Idle character bit count starts after stop bit.
1 PE	**Parity Enable** — Enables hardware parity generation and checking. When parity is enabled, the most significant bit (MSB) of the data character (eighth or ninth data bit) is treated as the parity bit. 0 No hardware parity generation or checking. 1 Parity enabled.
0 PT	**Parity Type** — Provided parity is enabled (PE = 1), this bit selects even or odd parity. Odd parity means the total number of 1s in the data character, including the parity bit, is odd. Even parity means the total number of 1s in the data character, including the parity bit, is even. 0 Even parity. 1 Odd parity.

14.2.3 SCI Control Register 2 (SCIxC2)

This register can be read or written at any time.

	7	6	5	4	3	2	1	0
R W	TIE	TCIE	RIE	ILIE	TE	RE	RWU	SBK
Reset	0	0	0	0	0	0	0	0

Figure 14-7. SCI Control Register 2 (SCIxC2)

Table 14-4. SCIxC2 Field Descriptions

Field	Description
7 TIE	**Transmit Interrupt Enable (for TDRE)** 0 Hardware interrupts from TDRE disabled (use polling). 1 Hardware interrupt requested when TDRE flag is 1.
6 TCIE	**Transmission Complete Interrupt Enable (for TC)** 0 Hardware interrupts from TC disabled (use polling). 1 Hardware interrupt requested when TC flag is 1.
5 RIE	**Receiver Interrupt Enable (for RDRF)** 0 Hardware interrupts from RDRF disabled (use polling). 1 Hardware interrupt requested when RDRF flag is 1.
4 ILIE	**Idle Line Interrupt Enable (for IDLE)** 0 Hardware interrupts from IDLE disabled (use polling). 1 Hardware interrupt requested when IDLE flag is 1.

Table 15-1. SPIxC1 Field Descriptions

Field	Description
7 SPIE	**SPI Interrupt Enable (for SPRF and MODF)** — This is the interrupt enable for SPI receive buffer full (SPRF) and mode fault (MODF) events. 0 Interrupts from SPRF and MODF inhibited (use polling) 1 When SPRF or MODF is 1, request a hardware interrupt
6 SPE	**SPI System Enable** — This bit enables the SPI system and dedicates the SPI port pins to SPI system functions. If SPE is cleared, SPI is disabled and forced into idle state, and all status bits in the SPIxS register are reset. 0 SPI system inactive 1 SPI system enabled
5 SPTIE	**SPI Transmit Interrupt Enable** — This is the interrupt enable bit for SPI transmit buffer empty (SPTEF). 0 Interrupts from SPTEF inhibited (use polling) 1 When SPTEF is 1, hardware interrupt requested
4 MSTR	**Master/Slave Mode Select —** This bit selects master or slave mode operation. 0 SPI module configured as a slave SPI device 1 SPI module configured as a master SPI device
3 CPOL	**Clock Polarity** — This bit selects an inverted or non-inverted SPI clock. To transmit data between SPI modules, the SPI modules must have identical CPOL values. This bit effectively places an inverter in series with the clock signal from a master SPI or to a slave SPI device. Refer to Section 15.4.5, “SPI Clock Formats” for more details. 0 Active-high SPI clock (idles low) 1 Active-low SPI clock (idles high)
2 CPHA	**Clock Phase** — This bit selects one of two clock formats for different kinds of synchronous serial peripheral devices. Refer to Section 15.4.5, “SPI Clock Formats” for more details. 0 First edge on SPSCK occurs at the middle of the first cycle of a data transfer 1 First edge on SPSCK occurs at the start of the first cycle of a data transfer
1 SSOE	**Slave Select Output Enable** — This bit is used in combination with the mode fault enable (MODFEN) bit in SPIxC2 and the master/slave (MSTR) control bit to determine the function of the $\overline{SS}$ pin as shown in Table 15-2.
0 LSBFE	**LSB First (Shifter Direction) —** This bit does not affect the position of the MSB and LSB in the data register. Reads and writes of the data register always have the MSB in bit 7 (or bit 15 in 16-bit mode). 0 SPI serial data transfers start with most significant bit 1 SPI serial data transfers start with least significant bit

Table 15-2. $\overline{SS}$ Pin Function

MODFEN	SSOE	Master Mode	Slave Mode
0	0	General-purpose I/O (not SPI)	Slave select input
0	1	General-purpose I/O (not SPI)	Slave select input
1	0	$\overline{SS}$ input for mode fault	Slave select input
1	1	Automatic $\overline{SS}$ output	Slave select input

15.3.2 SPI Control Register 2 (SPIxC2)

This read/write register is used to control optional features of the SPI system. Bits 6 and 5 are not implemented and always read 0.

The baud rate divisor equation is as follows:

$$BaudRateDivisor = (SPPR + 1) \xi 2^{(SPR + 1)}$$

The baud rate can be calculated with the following equation:

$$Baud\ Rate = \frac{BusClock}{BaudRateDivisor}$$

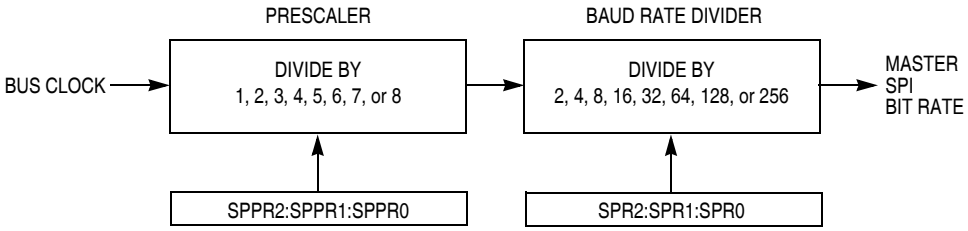


Figure 15-15. SPI Baud Rate Generation

15.4.7 Special Features

15.4.7.1 $\overline{SS}$ Output

The $\overline{SS}$ output feature automatically drives the $\overline{SS}$ pin low during transmission to select external devices and drives it high during idle to deselect external devices. When $\overline{SS}$ output is selected, the $\overline{SS}$ output pin is connected to the $\overline{SS}$ input pin of the external device.

The $\overline{SS}$ output is available only in master mode during normal SPI operation by asserting the SSOE and MODFEN bits as shown in Table 15-2.

The mode fault feature is disabled while $\overline{SS}$ output is enabled.

NOTE

Care must be taken when using the $\overline{SS}$ output feature in a multi-master system since the mode fault feature is not available for detecting system errors between masters.

15.4.7.2 Bidirectional Mode (MOMI or SISO)

The bidirectional mode is selected when the SPC0 bit is set in SPI Control Register 2 (see Table 15-9.) In this mode, the SPI uses only one serial data pin for the interface with external device(s). The MSTR bit decides which pin to use. The MOSI pin becomes the serial data I/O (MOMI) pin for the master mode, and the MISO pin becomes serial data I/O (SISO) pin for the slave mode. The MISO pin in master mode and MOSI pin in slave mode are not used by the SPI.

16.1.1 Features

The TPM includes these distinctive features:

- One to eight channels:
  - Each channel may be input capture, output compare, or edge-aligned PWM
  - Rising-Edge, falling-edge, or any-edge input capture trigger
  - Set, clear, or toggle output compare action
  - Selectable polarity on PWM outputs
- Module may be configured for buffered, center-aligned pulse-width-modulation (CPWM) on all channels
- Timer clock source selectable as prescaled bus clock, fixed system clock, or an external clock pin
  - Prescale taps for divide-by 1, 2, 4, 8, 16, 32, 64, or 128
  - Fixed system clock source are synchronized to the bus clock by an on-chip synchronization circuit
  - External clock pin may be shared with any timer channel pin or a separated input pin
- 16-bit free-running or modulo up/down count operation
- Timer system enable
- One interrupt per channel plus terminal count interrupt

16.1.2 Modes of Operation

In general, TPM channels may be independently configured to operate in input capture, output compare, or edge-aligned PWM modes. A control bit allows the whole TPM (all channels) to switch to center-aligned PWM mode. When center-aligned PWM mode is selected, input capture, output compare, and edge-aligned PWM functions are not available on any channels of this TPM module.

When the microcontroller is in active BDM background or BDM foreground mode, the TPM temporarily suspends all counting until the microcontroller returns to normal user operating mode. During stop mode, all system clocks, including the main oscillator, are stopped; therefore, the TPM is effectively disabled until clocks resume. During wait mode, the TPM continues to operate normally. Provided the TPM does not need to produce a real time reference or provide the interrupt source(s) needed to wake the MCU from wait mode, the user can save power by disabling TPM functions before entering wait mode.

- Input capture mode

  When a selected edge event occurs on the associated MCU pin, the current value of the 16-bit timer counter is captured into the channel value register and an interrupt flag bit is set. Rising edges, falling edges, any edge, or no edge (disable channel) may be selected as the active edge which triggers the input capture.
- Output compare mode

  When the value in the timer counter register matches the channel value register, an interrupt flag bit is set, and a selected output action is forced on the associated MCU pin. The output compare action may be selected to force the pin to zero, force the pin to one, toggle the pin, or ignore the pin (used for software timing functions).

	7	6	5	4	3	2	1	0
R	Bit 15	14	13	12	11	10	9	Bit 8
W	Any write to TPMxCNTH clears the 16-bit counter							
Reset	0	0	0	0	0	0	0	0

Figure 16-8. TPM Counter Register High (TPMxCNTH)

	7	6	5	4	3	2	1	0
R	Bit 7	6	5	4	3	2	1	Bit 0
W	Any write to TPMxCNTL clears the 16-bit counter							
Reset	0	0	0	0	0	0	0	0

Figure 16-9. TPM Counter Register Low (TPMxCNTL)

When BDM is active, the timer counter is frozen (this is the value that will be read by user); the coherency mechanism is frozen such that the buffer latches remain in the state they were in when the BDM became active, even if one or both counter halves are read while BDM is active. This assures that if the user was in the middle of reading a 16-bit register when BDM became active, it will read the appropriate value from the other half of the 16-bit value after returning to normal execution.

In BDM mode, writing any value to TPMxSC, TPMxCNTH or TPMxCNTL registers resets the read coherency mechanism of the TPMxCNTH:L registers, regardless of the data involved in the write.

16.3.3 TPM Counter Modulo Registers (TPMxMODH:TPMxMODL)

The read/write TPM modulo registers contain the modulo value for the TPM counter. After the TPM counter reaches the modulo value, the TPM counter resumes counting from 0x0000 at the next clock, and the overflow flag (TOF) becomes set. Writing to TPMxMODH or TPMxMODL inhibits the TOF bit and overflow interrupts until the other byte is written. Reset sets the TPM counter modulo registers to 0x0000 which results in a free running timer counter (modulo disabled).

Writing to either byte (TPMxMODH or TPMxMODL) latches the value into a buffer and the registers are updated with the value of their write buffer according to the value of CLKSB:CLKSA bits, so:

- If (CLKSB:CLKSA = 0:0), then the registers are updated when the second byte is written
- If (CLKSB:CLKSA not = 0:0), then the registers are updated after both bytes were written, and the TPM counter changes from (TPMxMODH:TPMxMODL - 1) to (TPMxMODH:TPMxMODL). If the TPM counter is a free-running counter, the update is made when the TPM counter changes from 0xFFFE to 0xFFFF

The latching mechanism may be manually reset by writing to the TPMxSC address (whether BDM is active or not).

When BDM is active, the coherency mechanism is frozen (unless reset by writing to TPMxSC register) such that the buffer latches remain in the state they were in when the BDM became active, even if one or both halves of the modulo register are written while BDM is active. Any write to the modulo registers bypasses the buffer latches and directly writes to the modulo register while BDM is active.

18.4.3.8 Debug Trigger Register (DBGT)

This register can be read any time, but may be written only if ARM = 0, except bits 4 and 5 are hard-wired to 0s.

	7	6	5	4	3	2	1	0
R	TRGSEL	BEGIN	0	0	TRG3	TRG2	TRG1	TRG0
W								
Reset	0	0	0	0	0	0	0	0

= Unimplemented or Reserved

Figure 18-8. Debug Trigger Register (DBGT)

Table 18-5. DBGT Register Field Descriptions

Field	Description
7 TRGSEL	**Trigger Type** — Controls whether the match outputs from comparators A and B are qualified with the opcode tracking logic in the debug module. If TRGSEL is set, a match signal from comparator A or B must propagate through the opcode tracking logic and a trigger event is only signalled to the FIFO logic if the opcode at the match address is actually executed. 0 Trigger on access to compare address (force) 1 Trigger if opcode at compare address is executed (tag)
6 BEGIN	**Begin/End Trigger Select** — Controls whether the FIFO starts filling at a trigger or fills in a circular manner until a trigger ends the capture of information. In event-only trigger modes, this bit is ignored and all debug runs are assumed to be begin traces. 0 Data stored in FIFO until trigger (end trace) 1 Trigger initiates data storage (begin trace)
3:0 TRG[3:0]	**Select Trigger Mode** — Selects one of nine triggering modes, as described below. 0000 A-only 0001 A OR B 0010 A Then B 0011 Event-only B (store data) 0100 A then event-only B (store data) 0101 A AND B data (full mode) 0110 A AND NOT B data (full mode) 0111 Inside range: A ≤ address ≤ B 1000 Outside range: address < A or address > B 1001 – 1111 (No trigger)

A.7 Supply Current Characteristics

Table A-7. Supply Current Characteristics

Num	C	Parameter	Symbol	V_{DD} (V)	Typical[1]	Max[2]	Unit
1	C	Run supply current[3] measured at (Core clock = 2 MHz, f_{Bus} = 1 MHz, BLPE mode)	RI_{DD}	5	1.1	1.6	mA
				3	0.8	1.5	
2	P	Run supply current[3] measured at (Core clock = 8 MHz, f_{Bus} = 4 MHz, FBE mode)		5	4.9	8	mA
				3	4.3	7	
3	C	Run supply current[3] measured at (Core clock = 48 MHz, f_{Bus} = 24 MHz, PEE mode)		5	23	30	mA
				3	22	30	
4	P	Stop2 mode supply current –40 °C 25 °C 85 °C	$S2I_{DD}$	5	0.80	3 3 20	µA
		–40 °C 25 °C 85 °C		3	0.80	3 3 20	µA
5	P	Stop3 mode supply current –40 °C 25 °C 85 °C	$S3I_{DD}$	5	0.90	3 3 20	µA
		–40 °C 25 °C 85 °C		3	0.90	3 3 20	µA
6	P	Adder to stop2 or stop3 for RTC enabled[4], 25°C	ΔI_{SRTC}	5	300		nA
				3	300		nA
7	P	Adder to stop3 for LVD enabled (LVDE = LVDSE = 1)	ΔI_{SLVD}	5	110		µA
				3	90		µA
8	P	Adder to stop3 for oscillator enabled[5] (ERCLKEN = 1 and EREFSTEN = 1)	ΔI_{SOSC}	5	5		µA
				3	5		µA
9	T	USB module enable current[6]	ΔI_{USBE}	5	1.5		mA
10	T	USB suspend current[7]	I_{SUSP}	5	270	500	µA

1 Typicals are measured at 25°C.

2 Values given here are preliminary estimates prior to completing characterization.

3 All modules except USB and ADC active, Oscillator disabled (ERCLKEN = 0), using external clock resource for input, and does not include any dc loads on port pins.

4 Most customers are expected to find that auto-wakeup from stop2 or stop3 can be used instead of the higher current wait mode. Wait mode typical is 560 µA at 5 V and 422 µA at 3V with f_{Bus} = 1 MHz.

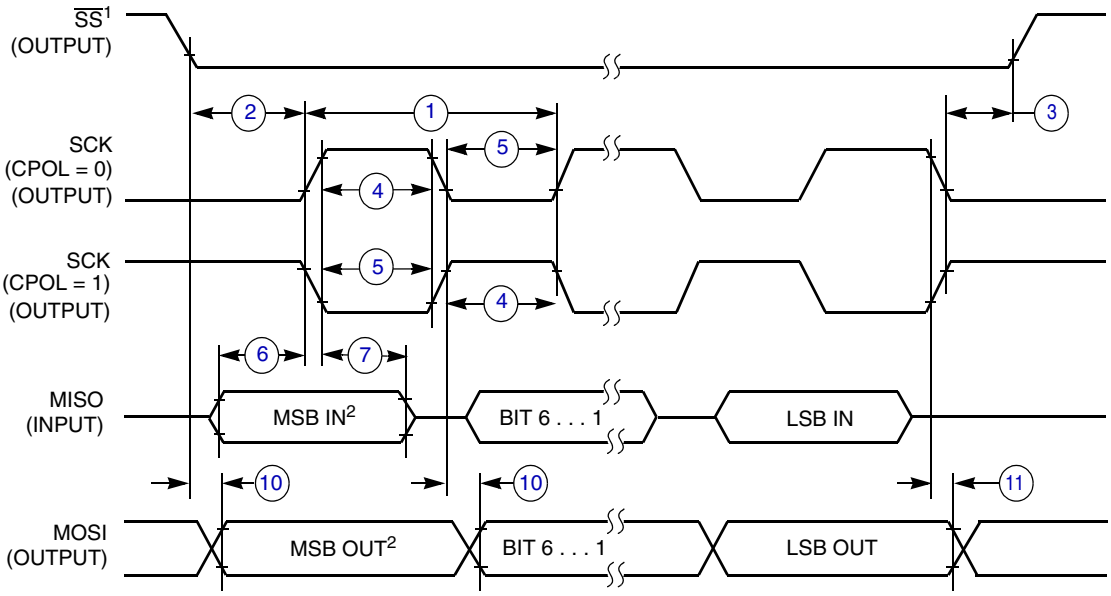
5 Values given under the following conditions: low range operation (RANGE = 0), low power mode (HGO = 0).

1 Refer to Figure A-10 through Figure A-13.

2 All timing is shown with respect to 20% V_{DD} and 70% V_{DD}, unless noted; 100 pF load on all SPI pins. All timing assumes slew rate control disabled and high drive strength enabled for SPI output pins.

3 Time to data active from high-impedance state.

4 Hold time to high-impedance state.



NOTES:
1. $\overline{SS}$ output mode (MODFEN = 1, SSOE = 1).
2. LSBF = 0. For LSBF = 1, bit order is LSB, bit 1, ..., bit 6, MSB.

Figure A-10. SPI Master Timing (CPHA = 0)